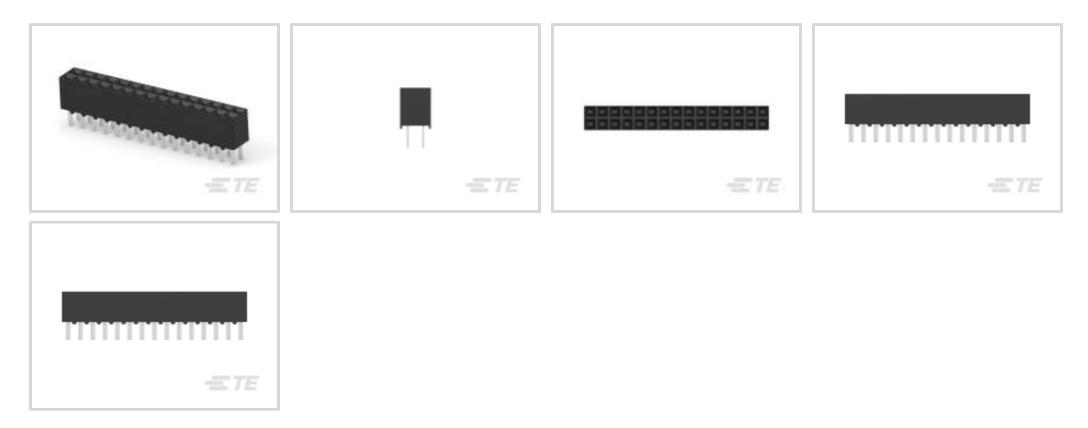


AMPMODU | Modu Connector System

TE Internal #: 6-534998-5 PCB Mount Receptacle, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 30

Number of Rows: 2

Features

E

Product Type Features

Applied Pressure	Standard
PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	30
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	750 VAC
Insulation Resistance	5000 ΜΩ

PCB Mount Receptacle, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Operating Voltage	333 VAC
Body Features	
Connector Profile	Low
Primary Product Color	Black
Contact Features	
Contact Protection Type	Closed Entry Housing
Contact Mating Area Length	3.77 mm[.148 in]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 7.61 μm
Contact Shape & Form	Round
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Socket
Contact Current Rating (Max)	2 A

Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.7 mm[.028 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Mating Entry Location	Тор
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Connector Height	5.03 mm[.198 in]

PCB Mount Receptacle, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	9.02 mm[.355 in]
PCB Thickness (Recommended)	1.57 mm[.055 – .094 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	15
Packaging Type	Box, Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous

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materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Modu Connector System



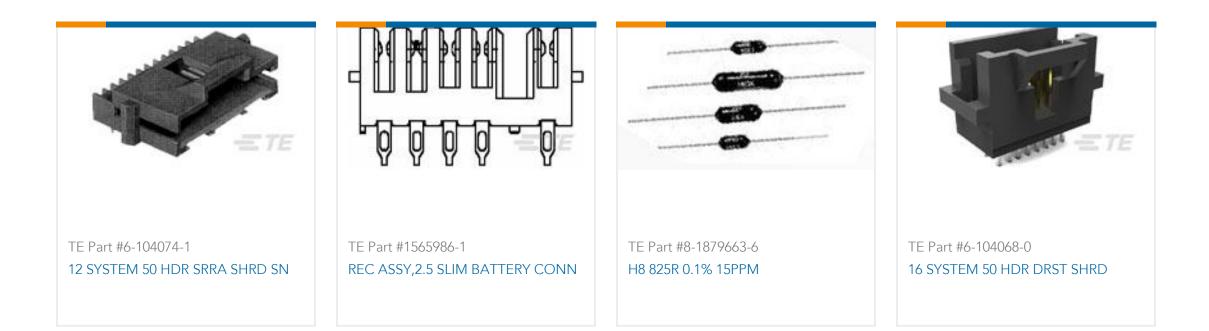
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PCB Headers & Receptacles(1245)	Standard Edge Connectors(2)

Customers Also Bought



PCB Mount Receptacle, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System





Documents

Product Drawings 30 MODIV VRT DR CE 100/125

English

CAD Files

Customer View Model

ENG_CVM_CVM_6-534998-5_R.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6-534998-5_R.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6-534998-5_R.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Specifications Application Specification

English